

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5703892

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JASPREET S. GANDHI	07/09/2015
DALE ARNOLD	07/13/2015
RECEIVING PARTY DATA	
Name:	MICRON TECHNOLOGY, INC.
Street Address:	8000 SOUTH FEDERAL WAY
City:	BOISE
State/Country:	IDAHO
Postal Code:	83716-9632
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16561906
CORRESPONDENCE DATA	
Fax Number:	(206)299-9288
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	206-903-8800
Email:	ip.docket.se@dorsey.com
Correspondent Name:	DORSEY & WHITNEY LLP-IP DEPT.-MTI
Address Line 1:	COLUMBIA CENTER
Address Line 2:	701 5TH AVENUE, SUITE 6100
Address Line 4:	SEATTLE, WASHINGTON 98104-7043
ATTORNEY DOCKET NUMBER:	P252489.US.03
NAME OF SUBMITTER:	ALEXANDRA LOUISE YAEGER
SIGNATURE:	/Alexandra L. Yaeger/
DATE SIGNED:	09/05/2019
Total Attachments: 3	
source=20150710_Assignment-signed_P252489US01 (copy)#page1.tif	
source=20150710_Assignment-signed_P252489US01 (copy)#page2.tif	
source=20150710_Assignment-signed_P252489US01 (copy)#page3.tif	

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

JASPREET S. GANDHI and DALE
ARNOLD

Filed : Concurrently herewith

For : SOLDER BOND SITE INCLUDING
AN OPENING WITH
DISCONTINUOUS PROFILE

Docket No. P252489.US.01

Disclosure No. 2014-0363.00/US

A S S I G N M E N T :

Enclosed for recording

Previously recorded

Date: _____

Reel: _____

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, the undersigned do hereby:

SELL, ASSIGN AND TRANSFER to **Micron Technology, Inc.** (the "Assignee"), a corporation of Delaware, having a place of business at 8000 South Federal Way, Boise, Idaho 83716-9632, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith and is entitled "**SOLDER BOND SITE INCLUDING AN OPENING WITH DISCONTINUOUS PROFILE**"; such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States of America;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to

Dale Arnold
Dale Arnold

Date: 7-13-2015

STATE OF IDAHO)
) ss.
County of Ada)

BEFORE ME, this 13th day of July, 2015, personally appeared the above-named individual, to me known to be the person who is described in and who executed the foregoing assignment instrument and acknowledged to me that he executed the same of his own free will for the purpose therein expressed.

SEAL



Diane V. Rangel
Notary or Consular Officer
My Commission Expires 6-30-17